

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3256246

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SEBASTIAN TAEGER	01/21/2015
MICHAEL HUBER	01/21/2015
KARL ENGL	01/21/2015
MARTIN WELZEL	02/05/2015
RECEIVING PARTY DATA	
Name:	OSRAM OPTO SEMICONDUCTORS GMBH
Street Address:	LEIBNIZSTR. 4
City:	REGENSBURG
State/Country:	GERMANY
Postal Code:	93055
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14413029
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	IP GROUP OF DLA PIPER LLP (US)
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ATTORNEY DOCKET NUMBER:	EHF-14-2493
NAME OF SUBMITTER:	T. DANIEL CHRISTENBURY
SIGNATURE:	/tdc/
DATE SIGNED:	03/09/2015
Total Attachments: 11	
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ASSIGNMENT

For good and valuable consideration, I (We),

Sebastian Taeger,
residing at ~~Heinestr. 3 a~~ *Thomas-Dittler-Str. 7*
93077 Bad Abbach
Germany
citizen of Germany

S. Tee 21 January 2011

Michael Huber,
residing at Buchenweg 2
93077 Bad Abbach
Germany
citizen of Germany

Martin Welzel,
residing at Lindenstr. 7a
01109 Dresden
Germany
citizen of Germany

Karl Engl,
residing at Rehfeld 25 a
93080 Pentling
Germany
citizen of Germany

hereafter individually or collectively referred to as "Assignor(s)";

Hereby, (i) acknowledge having previously assigned, sold and transferred to **OSRAM Opto Semiconductors GmbH**, a corporation organized and existing under the laws of GERMANY, having its principal place of business at Leibnizstr. 4 in 93055 Regensburg, hereinafter "Assignee", its successors, assigns and legal representatives, or to a predecessor of Assignee, pursuant to (A)(i) the laws of GERMANY or (ii) a Patent & Secrecy Agreement or similar legal document such as, without limitation, an employee agreement executed at the time of entering into the employment of, or executed as a condition of continuing employment with, the Assignee or a predecessor of the Assignee, the entire right, including any and all priority rights, title and interest, in and for the United States and all foreign countries, in and to any and all inventions or improvements which are disclosed in an invention disclosure and/or in the below-identified documents currently filed with this Assignment, already filed or granted for Letters Patent (in which case, any provision of the subject Assignment that is in conflict with or is in addition to any provision in the prior agreement(s) or assignment(s) then this Assignment shall govern, take precedence, and be of legal effect), or

(B)(i) to the extent such laws of GERMANY or such Patent & Secrecy Agreement or similar legal document failed or fails, in whole or part, to have assigned, sold or transferred the entire right (including priority rights), title and interest, in and for the United States and all foreign countries, in and to all inventions or improvements which are disclosed in the below-identified application(s) or pending application(s) or granted Letters Patent, or (ii) if no such agreement(s) exist assigning,

selling or transferring any such right (including priority rights), title or interest; then for good and valuable consideration, Assignor(s) now and hereby, effective Nunc Pro Tunc on the filing date of the below identified patent application(s), pending patent application(s) or granted Letter Patent(s), assign, sell and transfer(s) to Assignee, its successors, assigns and legal representatives, the entire right, (including all priority rights), title and interest in and for the United States and all foreign countries, in and to any and all inventions and/or improvements which are disclosed in the following identified; patent application(s), pending patent application(s) or granted Letter Patent(s)

Patent Application Title: METHOD OF ENCAPSULATING AN OPTOELECTRONIC
DEVICE AND LIGHT-EMITTING DIODE CHIP
Filing Date: 01/06/2015 (MM/DD/YYYY)
Filing Number: 14/413,029
Internal Case Number(s): EHF-14-2493

and in and to said application(s) or granted patents and all applications claiming priority to said application or granted patent, including, without limitation, and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of the inventions and/or improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on the inventions and/or improvements;

(II) Agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and or improvements and all applications for patents and all patents on said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and

(III) Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

S. Hupp
Witness Signature

Sebastian Taeger
Sebastian Taeger

Sophia Huppman
printed name of witness

21 January 2015
Date

ASSIGNMENT

For good and valuable consideration, I (We),

Sebastian Taeger,
residing at Heinestr. 3 a
93077 Bad Abbach
Germany
citizen of Germany

Michael Huber,
residing at Buchenweg 2
93077 Bad Abbach
Germany
citizen of Germany

Martin Welzel,
residing at Lindenstr. 7a
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Germany
citizen of Germany

Karl Engl,
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.....
Witness Signature

.....
Sebastian Taeger

.....
printed name of witness

.....
Date

Brendan Holland
Witness Signature

Michael Huber
Michael Huber

BRENDAN HOLLAND
printed name of witness

21 Jan 2015
Date

Witness Signature

printed name of witness

Martin Welzel

Date

Karl Engl
Witness Signature

Karl Engl
Karl Engl

BRENDAN HOLLAND
printed name of witness

21. January 2015
Date

Companies Representative(s)
OSRAM Opto Semiconductors GmbH

Signature
Name

Date

Signature
Name

Date

ASSIGNMENT

For good and valuable consideration, I (We),

Sebastian Taeger,
residing at Heinestr. 3 a
93077 Bad Abbach
Germany
citizen of Germany

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residing at Buchenweg 2
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citizen of Germany

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.....
Witness Signature

.....
Sebastian Taeger

.....
printed name of witness

.....
Date

Witness Signature

Michael Huber

printed name of witness

Date

Nicole Jauter

Witness Signature

Martin Welzel

Martin Welzel

Nicole Jauter

printed name of witness

5.02.2015

Date

Witness Signature

Karl Engl

printed name of witness

Date

Companies Representative(s)
OSRAM Opto Semiconductors GmbH

Signature

Name

Date

Signature

Name

Date

ASSIGNMENT

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Witness Signature

Sebastian Taeger

printed name of witness

Date

Witness Signature

Michael Huber

printed name of witness

Date

Witness Signature

Martin Welzel

printed name of witness

Date

Witness Signature

Karl Engl

printed name of witness

Date

Companies Representative(s)
OSRAM Opto Semiconductors GmbH

Signature

Name Dr. Ulrich Steegmüller
Vice President & CTO

Date

Signature

Name NIKOLAUS GMEINWIESER
SENIOR MANAGER

Date

INTELLECTUAL PROPERTY

2-3, JAN. 2015